EuMA European Microwave Association

Notification

Call for Papers

International Journal of Microwave and Wireless Technologies

Special Issue on Flexible Electronics for Wireless Communication Systems

Mechanical flexibility is a key feature of future electronics, as it will enable bendability, foldability, and stretchability of active modules. Emerging technologies – such as modern TOLAE (thin film organic and large area electronics), metal-oxide, carbon allotrope, or thinned silicon – can provide mechanical flexibility and are often associated with further attractive characteristics: light weight, ultra thinness, transparency, low cost, large-area and textile integration, washability, biocompatibility and easy recyclability.
With cut-off frequencies up to 100 MHz and bending radii down to 50 µm TOLAE transistors will enable the integration of wireless communication systems on ultra-thin, bendable and flexible substrates such as plastic or paper. These flexible communication systems will support novel applications in many diverse domains, from wearable electronics to environmental and medical monitoring.

The International Journal of Microwave and Wireless Technologies is soliciting articles for a Special Issue, which will cover all subjects related to Flexible Electronics for Wireless Communication Systems. **Manuscripts should be 6-8 pages in length, including figures and references.**

Relevant topics of interest include, but are not limited to:

- Emerging mechanically flexible RFIC technologies
- TOLAE technologies
- Metal-Oxide technologies
- Carbon allotrope technologies
- Thinned silicon technologies
- Flexible packaging and integration
- RF characterization and modelling of devices, including integrated antennas
- RF system and circuit design; Emerging applications.

Contributors are invited to submit their papers through the electronic submission system at the following address: http://mc.manuscriptcentral.com/mrf
When filling in the manuscript information, authors should select the "YES" tag in the Special Issue field, and choose "Special Issue on FFlexCom" in the following field.
Any further questions can be addressed to the Invited Editors:

Frank Ellinger (frank.ellinger@tu-dresden.de) ; Tilo Meister (tilo@ieee.org)
The deadline for submission of manuscripts is October 18, 2018
The proposed publication date for the Special Issue is May 2019.

Upon acceptance, your paper will be published in print, as well as electronically through Cambridge Journals Online (http://journals.cambridge.org/mrf). IJMWT publishes all accepted papers online ahead of print in FirstView. All papers are given a Digital Object Identifier (DOI), which enables them to be referenced as soon as they appear online.

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About the Journal

The International Journal of Microwave and Wireless Technologies is publishing ten issues a year. The official journal of the EuMA (**European Microwave Association**) aims to reinforce the presence of European Microwaves in the landscape of the scientific and technical literature. IJMWT provides academic and industrial researchers with an opportunity to promote their work and to stay connected with the most recent developments of Microwaves and Wireless technologies. The journal is published in association with Cambridge University Press, is disseminated worldwide in print and through the Cambridge Journals Online platform, and has an impact factor of 0.976.